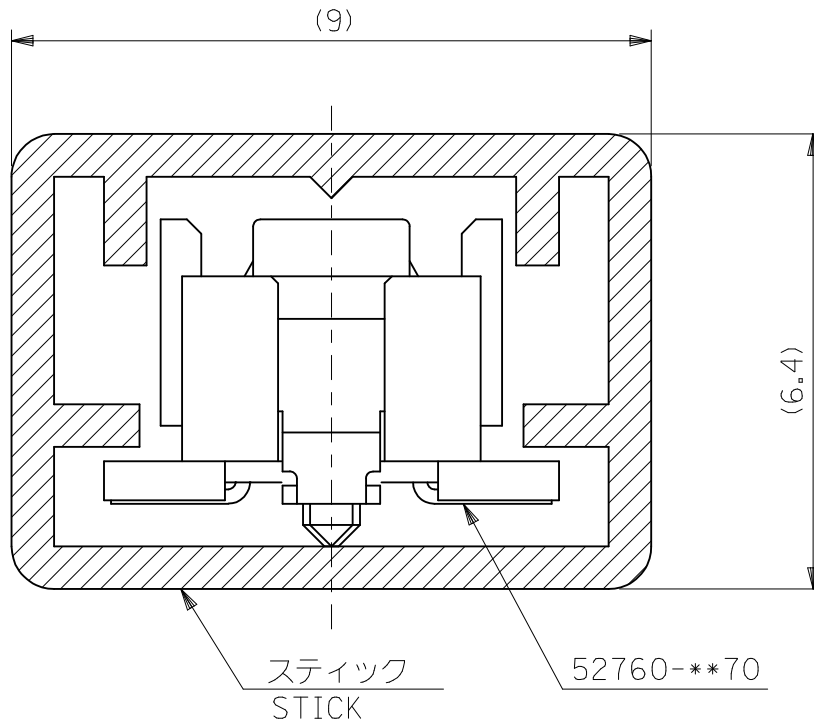


7 6 5 4 3 2 1



注)  
NOTES.

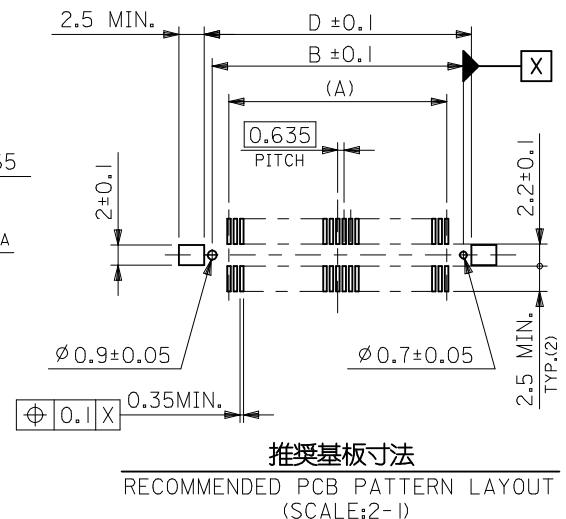
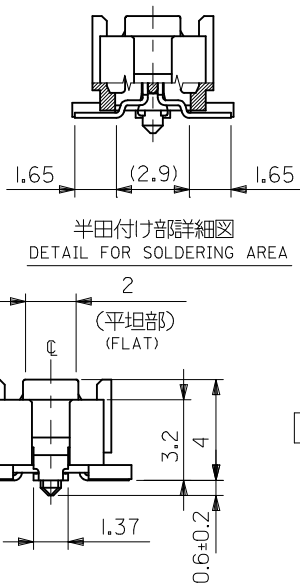
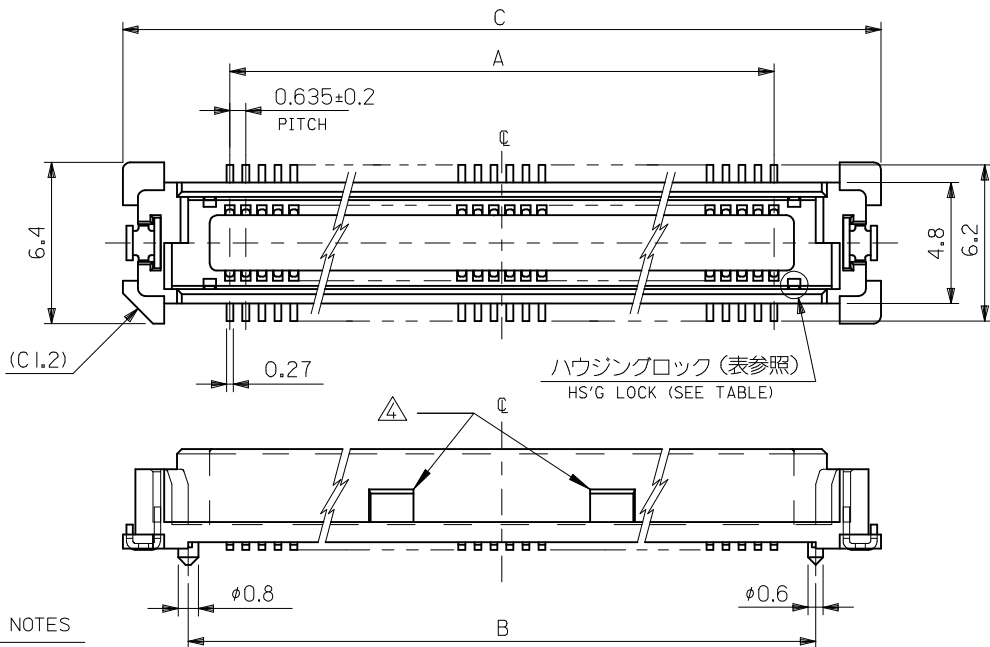
1. スティック両端はキャップ止め。  
BOTH ENDS WITH CAPS.
2. 全長： 600±2  
TOTAL LENGTH
3. 肉厚：0.6±0.2  
THICKNESS
4. 量産対応済の極数については、  
SD-52760-013を参照下さい。  
SEE SD-52760-013 FOR AVAIRABLE ITEMS.
5. 本製品は52760-\*\*\*9の鉛フリー品  
である。  
THIS PRODUCT IS LEAD FREE OF 52760-\*\*\*9.

6	52760-2479	240
7	↑ -2079	200
8	↓ -1879	180
9	↓ -1679	160
23	52760-0579	50
梱包数 QUANTITY	MATERIAL NO.	極数 NO. OF CKT.

REVISED EC NO: J2017-0575 DRWN:GES CHKD: APPR:MSASAO	2017/05/15 2017/06/29	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		0.25 UNDER	±	DRAWN BY	DATE	52760-***70 STICK PACKAGING -LEAD FREE- <b>molex</b> DOCUMENT NO. SD-52760-015 SHEET NO. 1 OF 1				
		0.25 OVER 0.5 UNDER	±	Y. WADA	2004/02/26					
		0.5 OVER 1.0 UNDER	±	CHECKED BY	DATE					
		0 OVER 10 UNDER	±0.2	M. SASAO	2004/02/26					
		10 OVER 30 UNDER	±0.25	APPROVED BY	DATE					
30 OVER	±0.3	M. SASAO	2004/02/26							
ANGULAR ±3 °		MATERIAL NO.		SEE CHART						
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				SIZE A4	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1



注記 NOTES

- 材質  
MATERIAL  
ハウジング : ガラス入り LCP、白色、UL94V-0  
HOUSING: G.F.LCP, WHITE, UL94V-0  
ターミナル : 銅合金 (t=0.2)  
TERMINAL: COPPER ALLOY  
ネイル : 銅合金 (t=0.25)  
NAIL: COPPER ALLOY
- メッキ仕様  
PLATING  
ターミナル : 接点部 : 金メッキ 0.25 μm MIN.  
TERMINAL : CONTACT AREA; GOLD 0.25 MICROMETER MIN.  
半田付け部 : 錫メッキ 2.0 μm MIN.  
SOLDER TAIL AREA; TIN 2.0 MICROMETER MIN.  
下地メッキ : ニッケルメッキ 2.0 μm MIN.  
UNDER-PLATING: NICKEL 2.0 MICROMETER MIN.  
補強金具 : 錫メッキ 1.0 μm MIN.  
FITTING NAIL : TIN 1.0 MICROMETER MINIMUM  
下地メッキ : ニッケルメッキ 1.0 μm MIN.  
UNDER-PLATING: NICKEL 1.0 MICROMETER MIN.

10 mm	53553 SERIES
9 mm	53552 SERIES
8 mm	53551 SERIES
7 mm	53481 SERIES
6 mm	53467 SERIES
5 mm	53475 SERIES
基板間寸法 STACKING HEIGHT	嵌合相手 TO BE MATED WITH

WITHOUT HSG LOCK	80.47	84.07	78.87	75.565	—	52760-2479	240
	67.77	71.37	66.17	62.865	—	52760-2079	200
	61.42	65.02	59.82	56.515	—	52760-1879	180
WITH HSG LOCK	55.07	58.67	53.47	50.165	—	52760-1679	160
	23.32	26.92	21.72	18.415	52760-0678	—	60
	20.15	23.75	18.55	15.24	52760-0578	52760-0579	50
D	C	B	A	EMBOSSED TAPE PACKAGE オーダー番号 ORDER NO.	STICK PACKAGE オーダー番号 ORDER NO.	極数 CIRCUITS	

CONNECTOR SERIES No. : 52760-\*\*\*70

- 200極以下のテール平坦度は 0.1 MAX.、  
TAIL COPLANARITY TO BE 0.1 MAX.  
240極のテール平坦度は 0.12 MAX. とする。  
IN 240 CIRCUITS, TAIL COPLANARITY TO BE 0.12 MAX.

△ 本製品は 2016 年 6 月 30日まで形状変更期間中となります。  
THIS PRODUCT IS DURING A FORM CHANGE PERIOD TILL JUNE 30, 2016.  
その為、図示形状が無い場合もございますが、製品機械性能上問題ございません。  
THEREFORE, THERE MAY NOT BE THE ILLUSTRATED SHAPE.  
HOWEVER, IT DOES NOT AFFECT ON CONNECTOR MECHANICAL PERFORMANCE.

REVISED EC NO: J2017-0575 DRWNGS CHKD: MSASAO APPR: MSASAO	2017/05/15	2017/06/29	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	DESCRIPTION	0.25 UNDER	UNDER	±0.03	DRAWN BY Y. WADA	DATE '04/02/26	TITLE 0.635 PITCH B-T0-B S/T REC. HSG ASSY -LEAD FREE-		
		0.25 OVER	0.5 UNDER	±0.05	CHECKED BY M. SASAO	DATE '04/02/26	DOCUMENT NO. SD-52760-013		
		0.5 OVER	1.0 UNDER	±0.1	APPROVED BY M. SASAO	DATE '04/02/26	SHEET NO. 1 OF 1		
	1.0 OVER	10 UNDER	±0.2	MATERIAL NO.		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
	10 OVER	30 UNDER	±0.25	SIZE A3					
	30 OVER		±0.3	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS					

9 8 7 6 5 4 3 2 1